

NOTES, UNLESS OTHERWISE SPECIFIED:

1. The netname "V5P0V" represents connection to the +5.0V power buss.
2. The netname "V3P3V" represents connection to the +3.3V power buss
3. The netname "V1P8V" represents connection to the +1.8V power buss
4. The netname "USB_VBUS" represents connection to the +5.0V USB host power buss.
5. The netname "SYS_PWR" represents connection to the +4.5V power buss.
6. The netname "GND" represents connection to the ground plane.
7. A "Z" suffix on a signal name indicates an active low signal.
8. All components with designators "U*", "Q*", and "D*" are electrostatic discharge sensitive.
9. All resistor values are in ohms.
10. All capacitor values in microfarads unless otherwise specified.



COMPUTER GENERATED DRAWING - DO NOT REVISE MANUALLY

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
-	Draft Release	07/24/2014	HPC
A	ECO 2143344: REV A Release		

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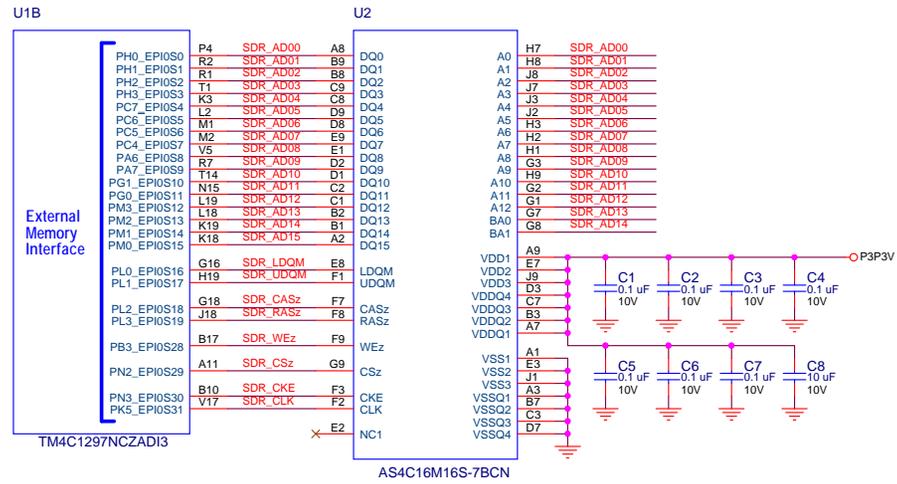
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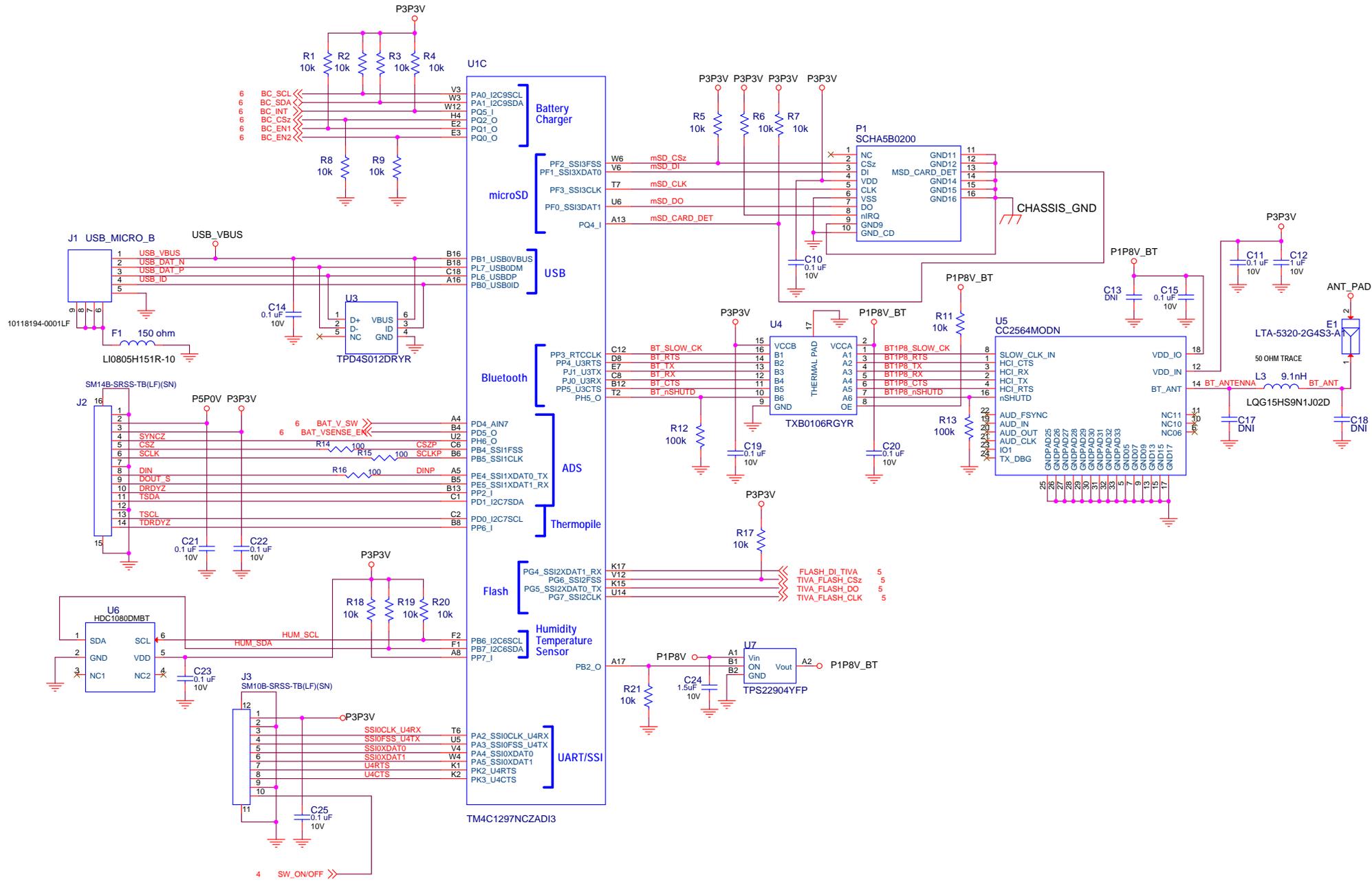
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	ENGR						
	APVD						
	MFG						
	0314CP	QA		TITLE			
NEXT ASSY	USED ON			ESD, NIRscan Nano Tiva Board			
	APPLICATION	SW	Allegro Design Entry 16.6	DRAWING NO	2514147	REV	E
				SCALE	SHEET 1 of 7		



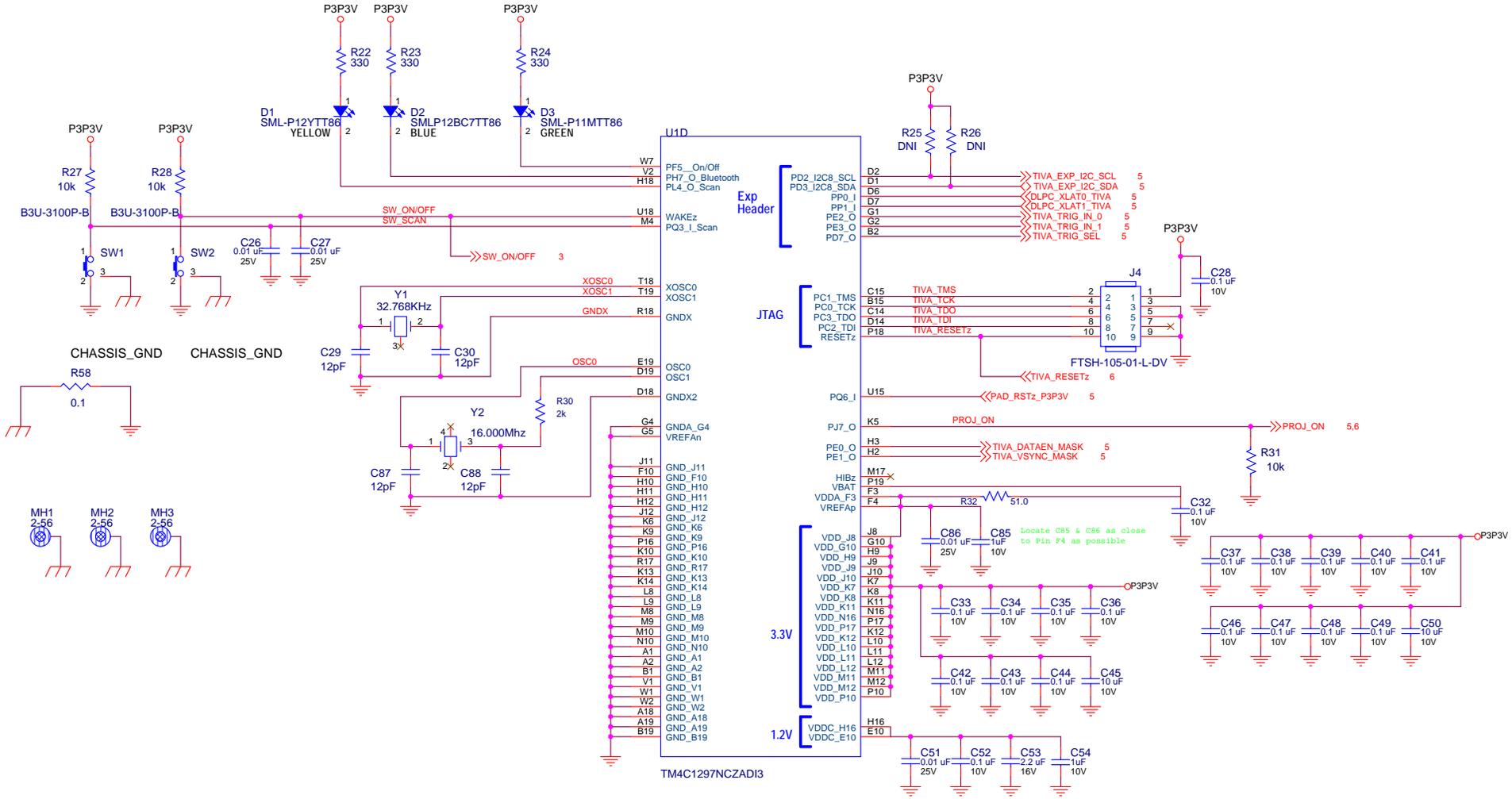
EXTERNAL MEMORY

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	ISSUE DATE				



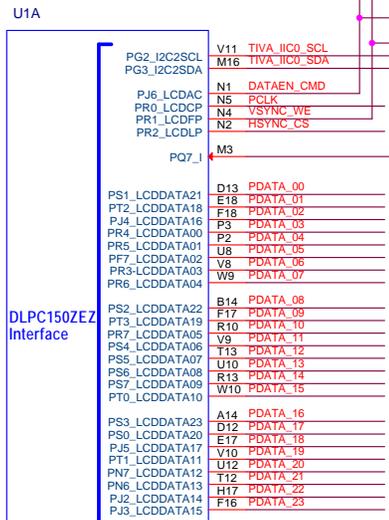
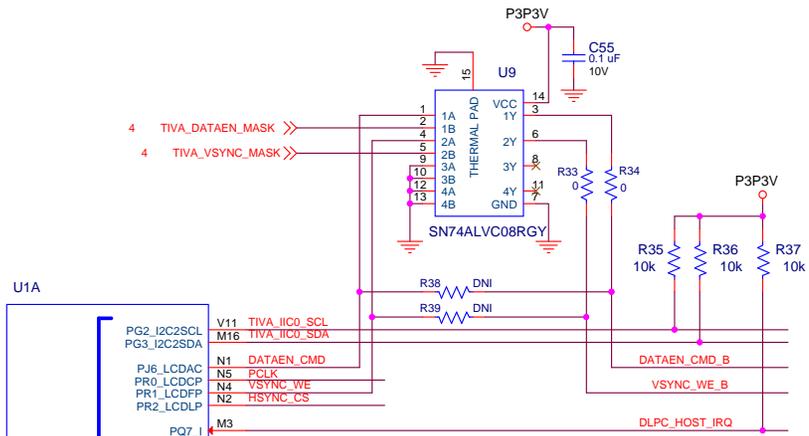
Peripherals

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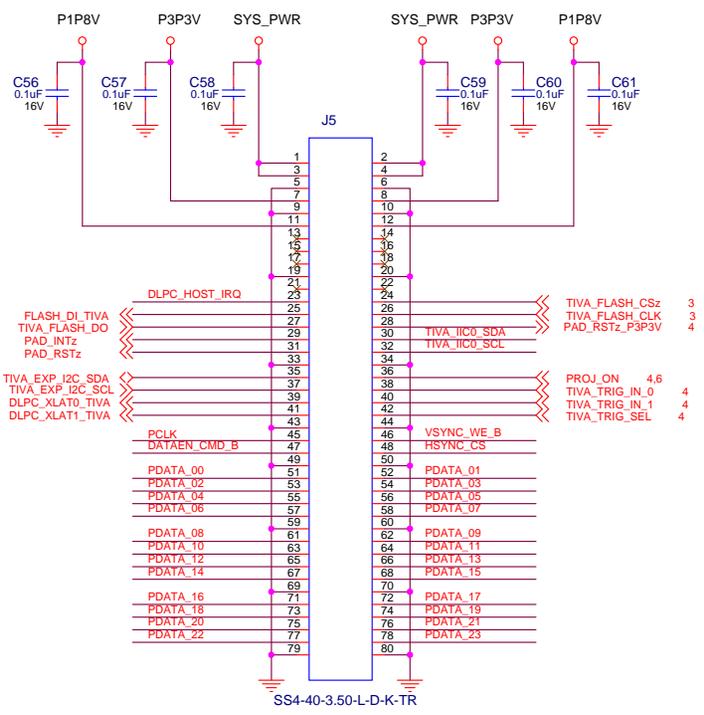


TIVA POWER & MISC

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	ISSUE DATE	SCALE		SHEET 4 OF 7	

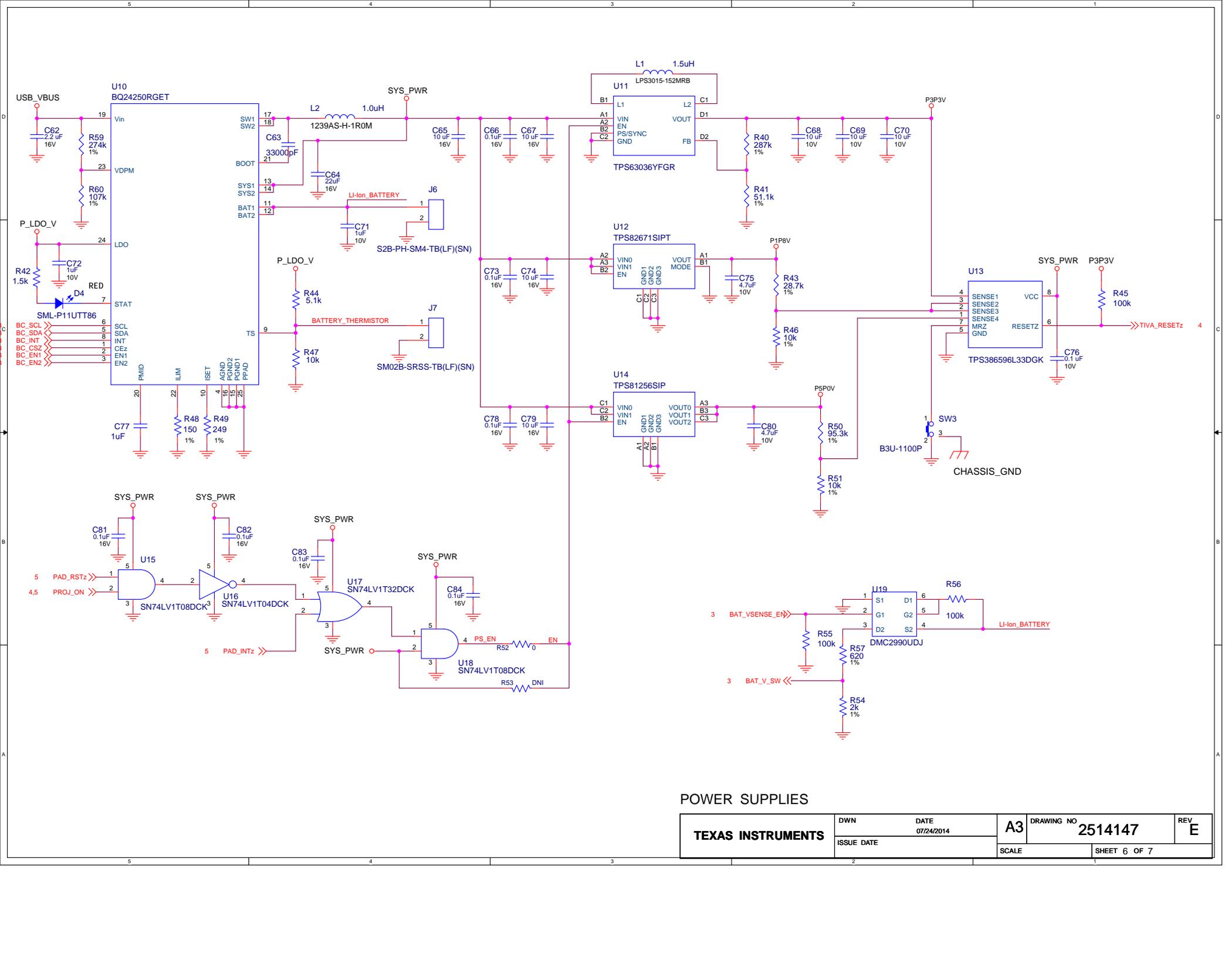


TM4C1297NCZAD13



TIVA PARALLEL & MISC INTERFACES

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POWER SUPPLIES

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	ISSUE DATE			SCALE	SHEET 6 OF 7

Revision History

Rev. -- : Draft Release ~ 07/24/2014

Rev. A: ECO 2143344: ~ 04/??/2014

Rev. A: (1) Added Thermal Pad Contacts to U4 and U9 08/21/2014 MR.
 (2) Added (3) 2-56 Mounting Holes. 08/21/2014 MR.
 (3) Added R58 0.1ohm resistor between chassis ground and common ground. 08/21/2014 MR.
 (4) Changed U1 part#TM4C1297NCZADI3 to TM4C1299NCZADI3 . 08/29/2014 MR.

Rev. B: C13 Changed to DNI 10/19/2014 MR.
 C12 Changed to 1uF 10/19/2014 MR.
 C24 Changed to 1uF 10/19/2014 MR.
 U10 Changed SYS PWR connections to pin13 & pin14.10/19/2014 MR.
 C64 Changed positive connection to U10 pin13 & pin14 and negative connection to GND 10/19/2014 MR.
 U8 removed, replace with Y2 add C87 and C88. page4 10/22/2014 MR.
 Added R59 & R60 voltage divider at U10. page6 10/31/2014 MR.

Rev. C: R26 and R26 Changed to DNI. 02/06/2015 PG.
 Changed U1 part#TM4C1299NCZADI3 to TM4C1297NCZADI3. 02/06/2015 PG.
 Changed R44 from DNI to 5.1k. 04/10/2015 MR.

Rev. D: P1 device changed net connections on pin9(GND) and pin13(MD_CARD_DET).

Rev. E: Changed U6 from HDC1000 to HDC1080 device type, package type changed from WPA-8 to WSON-6.

Schematic Revision History

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	ISSUE DATE	07/24/2014			
SCALE			SHEET 7 OF 7		